

MOSFET Silicon N-Channel MOS



1. Applications

Synchronous rectification in SMPS,
Hard switching and High speed circuit
DC/DC in telecoms and industrial

2. Features

Low drain-source on-resistance: $R_{DS(on)} = 1.9m\Omega$ (typ.)
High speed power switching
Enhanced body diode dv/dt capability
Enhanced avalanche ruggedness

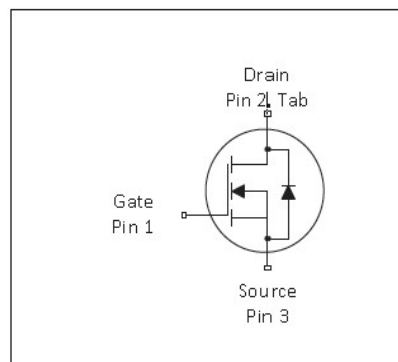
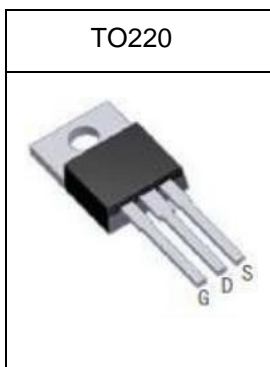


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	60	V
$R_{DS(on),max}$	2.3	m Ω
$Q_{g,typ}$	157.4	nC
$I_{D,pulse}$	870	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
AUP023N06	TO220	AUP023N06



1 Maximum ratings

At $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current at silicon ¹⁾	I_D		-	290	A	$T_C = 25^\circ\text{C}$
Continuous drain current at package ¹⁾	I_D		-	255	A	$T_C = 25^\circ\text{C}$
Continuous drain current at silicon ¹⁾	I_D			205	A	$T_C = 100^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,pulse}$	-		870	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	870	mJ	$T_C = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_{GS} = 10\text{V}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$
Avalanche current, single pulse	I_{AR}	-	-	59	A	$T_C = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Power dissipation	P_{tot}	-	-	310	W	$T_C = 25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	175	$^\circ\text{C}$	
Operating junction temperature	T_j	-55	-	175	$^\circ\text{C}$	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			300	$^\circ\text{C}$	

¹⁾Limited by $T_{j,max}$. Maximum Duty Cycle $D = 0.50$

²⁾Pulse width t_p limited by $T_{j,max}$

³⁾Identical low side and high side switch with identical R_G

2 Thermal characteristics

Table Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.48	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	60	°C/W	device on PCB, minimal footprint

3 Electrical characteristics

at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	60	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{(GS)th}$	2.5		4.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=60V, V_{GS}=0V, T_j=25^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}	-	-	+/-100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.9	2.3	m Ω	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Gate resistance (Intrinsic)	R_G	-	2.2	-	Ω	$f=1\text{MHz}$, open drain
Transconductance	G_{fs}		139.2		S	$V_{DS}=5V, I_D=50A$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	10843	-	pF	$V_{GS}=0V, V_{DS}=30V, f=1\text{MHz}$
Output capacitance	C_{oss}	-	3631	-	pF	$V_{GS}=0V, V_{DS}=30V, f=1\text{MHz}$
Reverse transfer capacitance	C_{riss}	-	185.9	-	pF	$V_{GS}=0V, V_{DS}=30V, f=1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	-	21	-	ns	$V_{DD}=30V, V_{GS}=10V, I_D=20A, R_G=2.5\Omega$
Rise time	t_r	-	49	-	ns	$V_{DD}=30V, V_{GS}=10V, I_D=20A, R_G=2.5\Omega$
Turn-off delay time	$t_{d(off)}$	-	90.2	-	ns	$V_{DD}=30V, V_{GS}=10V, I_D=20A, R_G=2.5\Omega$
Fall time	t_f	-	58	-	ns	$V_{DD}=30V, V_{GS}=10V, I_D=20A, R_G=2.5\Omega$

Table 6 Gate charge characteristics

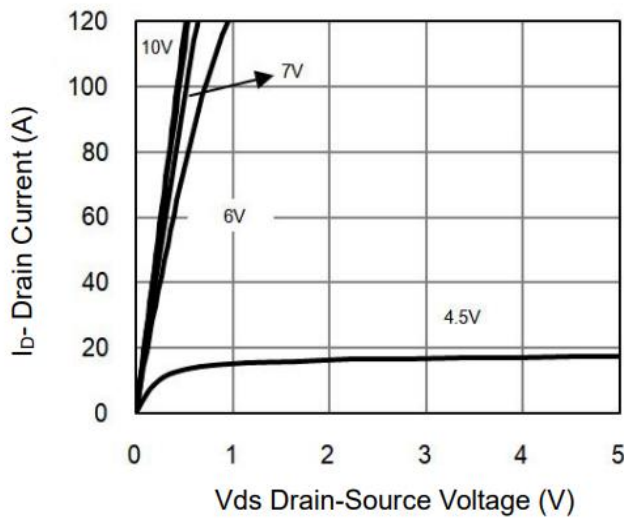
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	42.9	-	nC	$V_{DD}=30V, I_D=20A, V_{GS}=10V$
Gate to drain charge	Q_{gd}	-	30.5	-	nC	$V_{DD}=30V, I_D=20A, V_{GS}=10V$
Gate charge total	Q_g	-	157.4	-	nC	$V_{DD}=30V, I_D=20A, V_{GS}=10V$

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.67	1.2	V	$V_{GS}=0V, I_s=1A, T_j=25^{\circ}C$
Reverse recovery time	t_{rr}	-	128.9	-	ns	$V_{GS}=0V, I_F=20A, di_F/dt=100A/\mu s$
Reverse recovery charge	Q_{rr}	-	252.9	-	nC	$V_{GS}=0V, I_F=20A, di_F/dt=100A/\mu s$
Peak Reverse Recovery Current	I_{rrm}	-	3.3	-	A	$V_{GS}=0V, I_F=20A, di_F/dt=100A/\mu s$

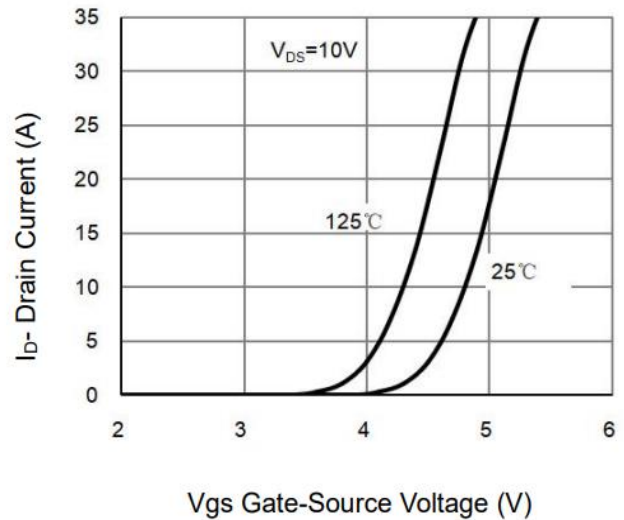
4 Electrical characteristics diagram

Diagram 1: Typ. Output characteristics



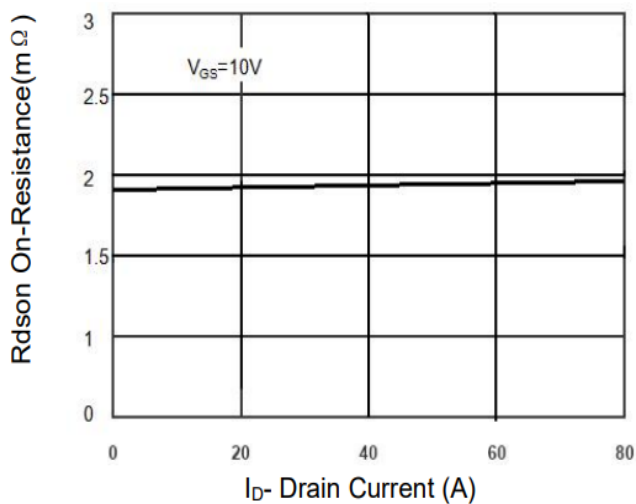
$I_D = f(V_{DS}); T_j = 25^\circ\text{C};$ parameter: V_{GS}

Diagram 2: Typ. Transfer characteristics



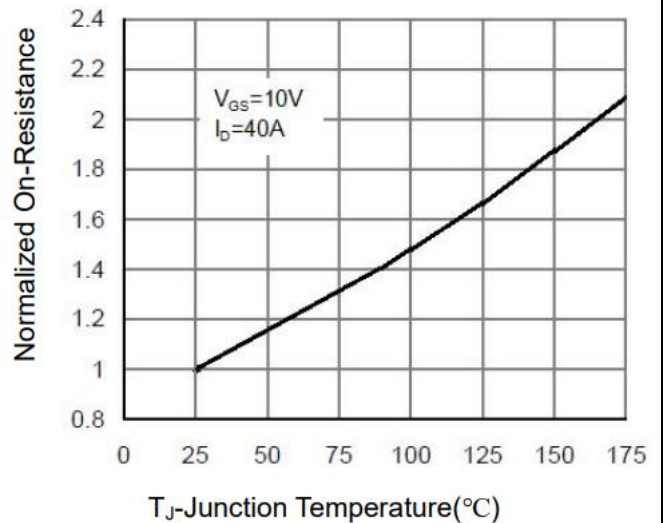
$I_D = f(V_{GS});$ parameter: T_j

Diagram 3: Typ. Rds(on) vs. Drain Current



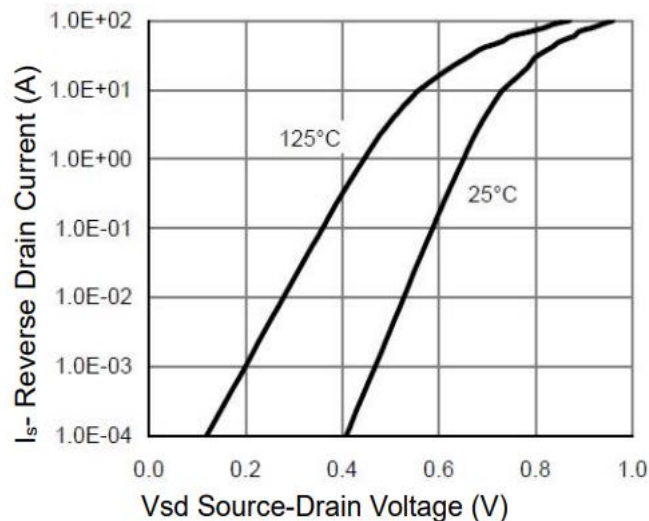
$R_{DS(on)} = f(I_D); V_{GS} = 10V$

Diagram 4: Typ. Rds(on) – Junction Temperature



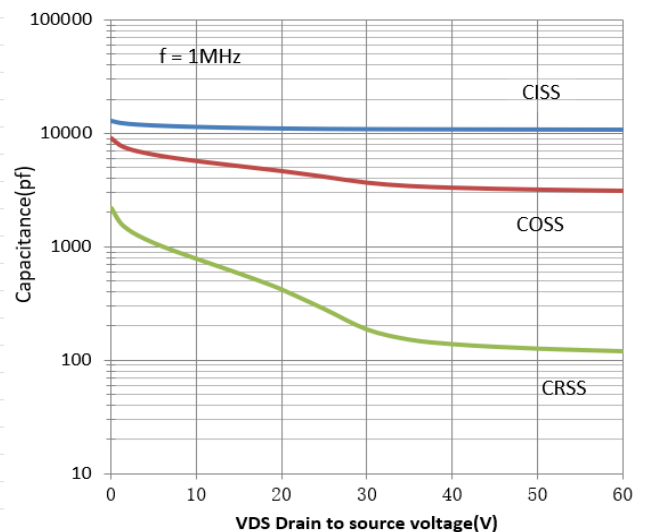
$R_{DS(on)} = f(T_j); V_{GS} = 10V / I_D = 40A$

Diagram 5: Typ. Body-Diode Characteristics



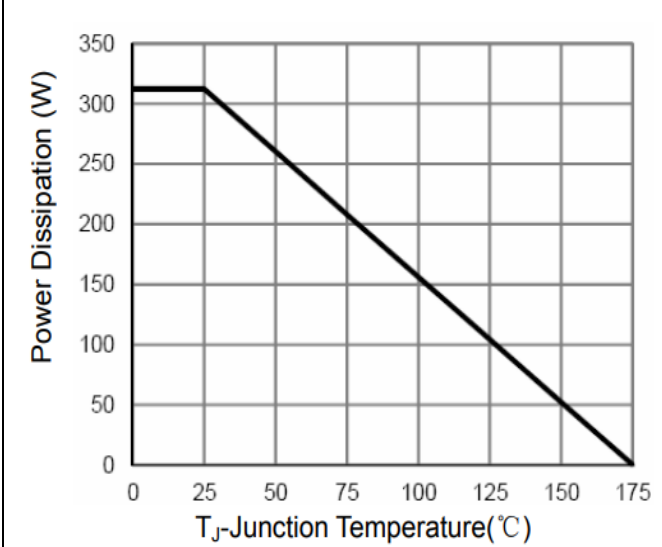
$I_S = f(V_{SD});$ parameter: T_j

Diagram 6: Typ. Capacitance vs. Vds



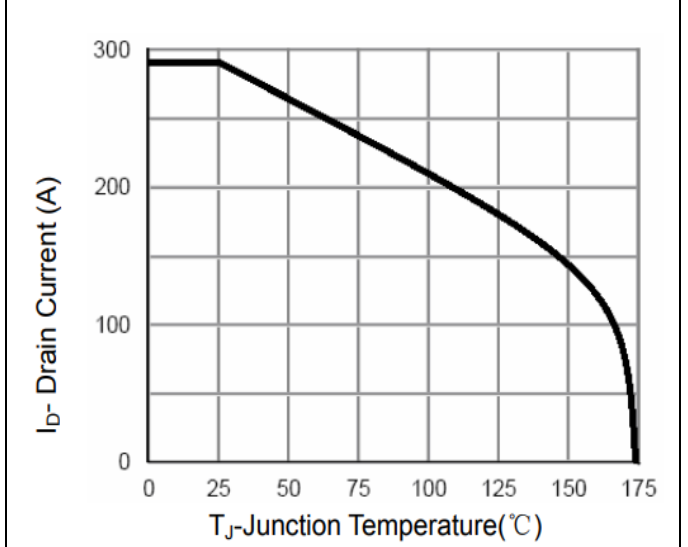
$C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$

Diagram 7: Typ. Power Dissipation



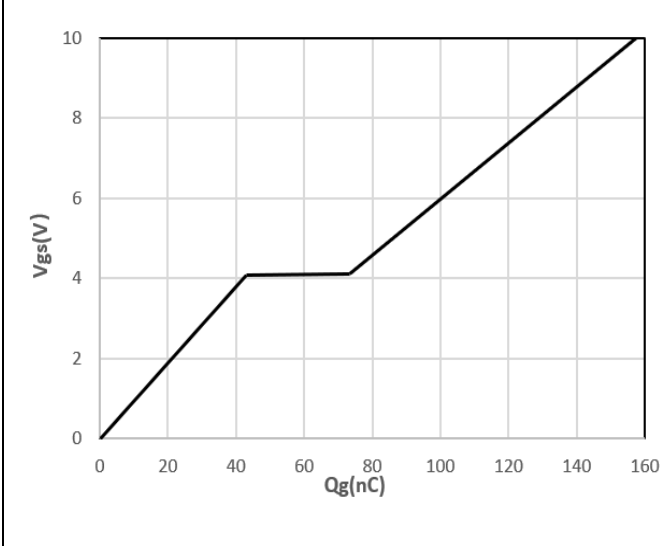
$P_{tot}=f(T_C)$;

Diagram 8: Typ. Drain Current De-rating



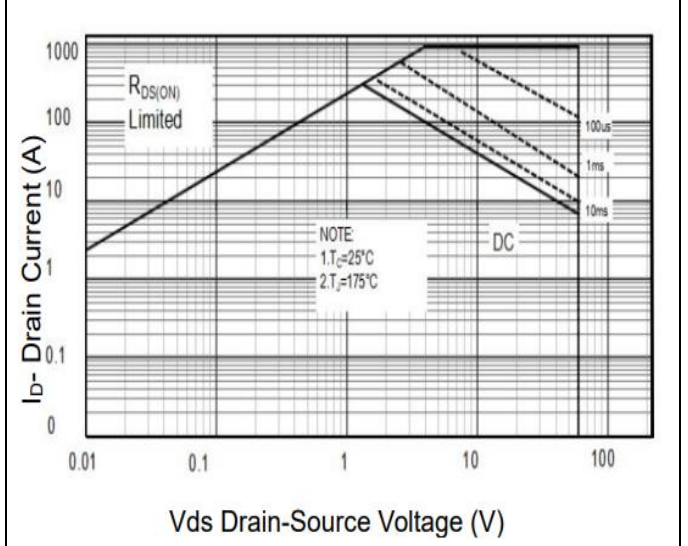
$I_d=f(T_C)$;

Diagram 9: Typ. Gate charge



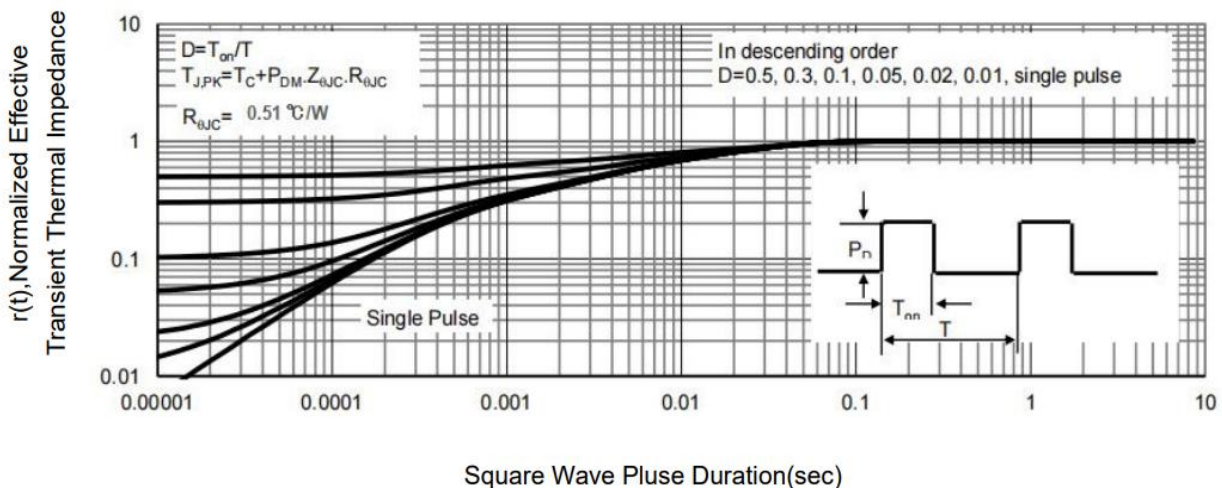
$V_{GS}=f(Q_{gate})$; I_b=20A pulsed; parameter: V_{DD}

Diagram 10: Typ. Maximum Safe Operating Area



$I_D=f(V_{DS})$; T_C=25 °C; V_{GS}> 7V; D=0; parameter tp

Figure 11 Normalized Maximum Transient Thermal Impedance



5. Package Outlines

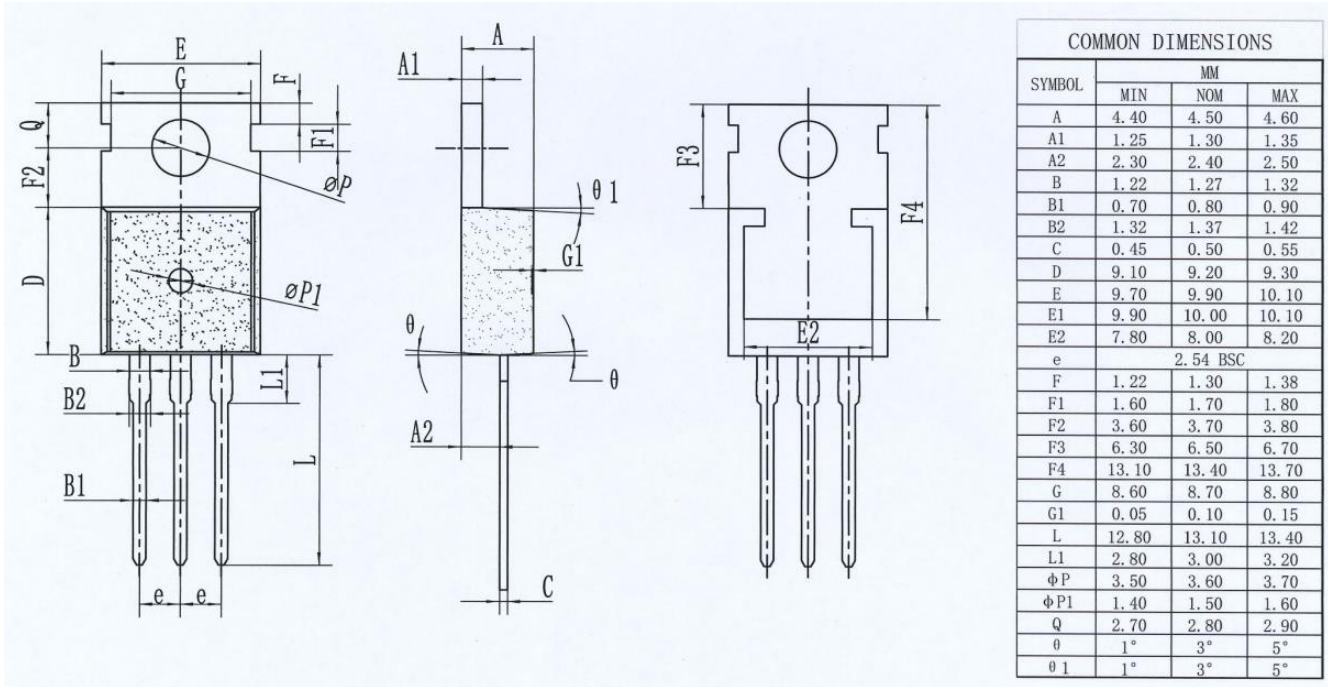


Figure: Outline PG-T0220(LM)

Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2023-06-05	Preliminary version

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